

3/11

03-11-2005



102957513

112955 U.S. PTO
11/069129



Form PTO-1595
(Rev. 03/01)

RECORDATION FORM C
PATENTS

COMMERCE
emark Office

OMB No. 0651-0027 (exp. 5/31/2002)

Tab settings ⇌ ⇌ ⇌ ▼ ▼ ▼ ▼ ▼ ▼

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

1. Yang Cheng Hung
2. Kuo Liang Lu
3. Tseng Wen Song
4. Chen Peir Horng

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies)

Name: Taiwan Semiconductor Manufacturing Co., Ltd.

Internal Address: _____

Street Address: No. 8, Li-Hsin Road 6

Science Based Industrial Park

City: Hsin-Chu State: _____ Zip: _____

Country: Taiwan 300-77 R.O.C.

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

Assignment Merger

Security Agreement Change of Name

Other _____

Execution Date: 02/14/2005

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 02/14/2005

A. Patent Application No.(s) _____

B. Patent No.(s) _____

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: William H. Murray, Esquire

Internal Address: Duane Morris LLP

Street Address: One Liberty Place

City: Philadelphia State: PA Zip: 19103

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

Enclosed

Authorized to be charged to deposit account

8. Deposit account number:

04-1679

DO NOT USE THIS SPACE

9. Signature.

Steven E. Koffs Steven E. Koffs 03/01/2005

Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments, and documents: 3

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

03/10/2005 6TOM11 00000130 041679 11069129

01 FC:8021 (40.00 DA)

ASSIGNMENT AND AGREEMENT

For value received, we, **Yang Cheng Hung, Kuo Liang Lu, Tseng Wen Song, and Chen Peir Horng**, hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **NOVEL SEMICONDUCTOR WAFER LIFTER** described in an application for Letters Patent of the United States and all the rights and privileges in said applications and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.** the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize **Taiwan Semiconductor Manufacturing Co., Ltd.** to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of **Taiwan Semiconductor Manufacturing Co., Ltd.** to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to **Taiwan Semiconductor Manufacturing Co., Ltd.** in the United States and in all countries foreign to the United States, or to such nominees as **Taiwan Semiconductor Manufacturing Co., Ltd.** may designate.

PH1\1409933.1

1

P.02

TD 00212159791020

4477200 15:17 HJUM

PATENT
REEL: 016341 FRAME: 0893

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: 2005/2/14

Yang Cheng Hung
Yang Cheng Hung

Residence:

2F.-1, No. 196, Jhongjheng 5th St., Taoyuan City, Taoyuan County (330)
, Taiwan (R.O.C.)

Inventor No. 2

Dated: 2005/02/14

Kuo Liang Lu
Kuo Liang Lu

Residence:

16F.-1, NO. 10, Lane 175, Wuling Road, Hsinchu City 300, Taiwan (Rep.)

Inventor No. 3

Dated: 2/4 (2005)

Tseng Wen Song
Tseng Wen Song

Residence: NO. 49, Lane 450, sec. 2, Jhongsing Rd., Taitung City,
Taitung County 950, Taiwan (R.O.C.)

Inventor No. 4

Dated: 2005-02-14

Chen Peir Horng
Chen Peir Horng

Residence: 5F., No. 1, Lane 46, Ren-ai Rd., Taoyuan City, Taiwan (R.O.C.)